

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (canceled).
2. (previously presented): The heat-peelable pressure-sensitive adhesive sheet as claimed in claim 3, wherein the heat-expandable pressure-sensitive adhesive layer before heating has a center line average surface roughness of 2 μm or less.
3. (previously presented): A heat-peelable pressure-sensitive adhesive sheet comprising a substrate and formed on at least one side thereof a heat-expandable pressure-sensitive adhesive layer containing heat-expandable microspheres, wherein the heat-expandable pressure-sensitive adhesive layer has a surface resistivity of $10^{12} \Omega/\square$ or lower, and the heat-expandable pressure-sensitive adhesive layer before heating has a maximum surface roughness of 5 μm or less, and

wherein at least one selected from the group consisting of inorganic conductive materials, organic antistatic agents and organic conductive materials is contained in or applied to the heat-expandable pressure-sensitive adhesive layer.

4. (previously presented): The heat-peelable pressure-sensitive adhesive sheet as claimed in claim 3, which further comprises a rubber-like organic elastic layer interposed between the substrate and the heat-expandable pressure-sensitive adhesive layer.

5. (original): The heat-peelable pressure-sensitive adhesive sheet as claimed in claim 4, wherein the rubber-like organic elastic layer comprises a pressure-sensitive adhesive material.

6. (previously presented): The heat-peelable pressure-sensitive adhesive sheet as claimed in claim 3, wherein the at least one of inorganic conductive materials, organic antistatic agents and organic conductive materials is contained in the heat-expandable pressure-sensitive adhesive layer and is a conductive powder.

7. (previously presented): A heat-peelable pressure-sensitive adhesive sheet comprising a substrate and formed on at least one side thereof a heat-expandable pressure-sensitive adhesive layer containing heat-expandable microspheres, wherein the heat-expandable pressure-sensitive adhesive layer has a surface resistivity of $10^{12} \Omega/\square$ or lower, and the heat-expandable pressure-sensitive adhesive layer before heating has a maximum surface roughness of 5 μm or less, and

wherein at least one selected from the group consisting of inorganic conductive materials, organic antistatic agents and organic conductive materials is applied to the substrate.

8. (previously presented): The heat-peelable pressure-sensitive adhesive sheet as claimed in claim 7, wherein an organic antistatic agent layer is formed on at least one side of the substrate.

9. (previously presented): The heat-peelable pressure-sensitive adhesive sheet as claimed in claim 7, wherein the heat-expandable pressure-sensitive adhesive layer before heating has a center line average surface roughness of 2 μm or less.

10. (previously presented): The heat-peelable pressure-sensitive adhesive sheet as claimed in claim 7, which further comprises a rubber-like organic elastic layer interposed between the substrate and the heat-expandable pressure-sensitive adhesive layer.

11. (previously presented): The heat-peelable pressure-sensitive adhesive sheet as claimed in claim 10, wherein the rubber-like organic elastic layer comprises a pressure-sensitive adhesive material.

12. (new): The heat-peelable pressure-sensitive adhesive sheet as claimed in claim 7, wherein at least one selected from the group consisting of inorganic conductive materials and organic conductive materials is applied to the substrate.